



Title of Change:	Copper wire conversion for LV8282PV and LV8702V
Proposed first ship date:	17 October 2016
Contact information:	Contact your local ON Semiconductor Sales Office or <Tsutomu.Shimazaki@onsemi.com><Takashi.Harashima@onsemi.com><Takeshi2.Hoshino@onsemi.com><Kazumi.Onda@onsemi.com><Shinya.Okada@onsemi.com><Yoshiyuki.Nunokawa@onsemi.com>
Samples:	Contact your local ON Semiconductor Sales Office or <jun.hasunuma@onsemi.com>
Type of notification:	This is an Initial Product/Process Change Notification (IPCN) sent to customers. IPCNs are issued at least 30 days prior to the issuance of the Final Change Notice (FPCN). An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact <PCN.Support@onsemi.com>.
Change Part Identification:	Affected products will be identified with date code.
Change category:	<input type="checkbox"/> Wafer Fab Change <input checked="" type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input type="checkbox"/> Other _____
Change Sub-Category(s):	<input type="checkbox"/> Manufacturing Site Change/Addition <input checked="" type="checkbox"/> Material Change <input type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Manufacturing Process Change <input type="checkbox"/> Product specific change <input type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Other: _____
Sites Affected:	<input type="checkbox"/> All site(s) <input type="checkbox"/> not applicable <input checked="" type="checkbox"/> ON Semiconductor site(s) : ON Tarlac City, Philippines <input type="checkbox"/> External Foundry/Subcon site(s)
Description and Purpose:	<p>This is an Initial Process Change Notification to inform customers of the conversion of the Gold wire connecting chip and Lead to Copper wire for LV8282PV and LV8702V.</p> <p>There will be no change on the electrical characteristics of the Products.</p>

**Qualification Plan:**

DEVICE NAME : LV8282PV/LV8702V

Package name : SSOP44K/ SSOP44J(275mil)

Test	Specification	Condition	Interval
HTOL	EIAJ ED-4701/100	Tj=Tjmax, Vcc=Operatingmax	1000 hrs
THB*	EIAJ ED-4701/100	85°C, 85% RH, Vcc=recommended	1000 hrs
TC*	EIAJ ED-4701/100	Ta= -65°C to +150°C	100 cyc
AC*	EIAJ ED-4701-3	Ta=121°C ,RH=100% ,205kPa	50 hrs
HTSL	EIAJ ED-4701/200	Ta= 150°C	1000 hrs
RSH	EIAJ ED-4701/300	Ta = 255°C , 10 sec (peak 260°C)	2times

Notes:

The test items with * mark are put into operation after the reflow soldering (at 255degC for 10seconds) -> SMD
 Temperature Humidity Bias Test: PD>=0.1W -> Intermittent power application consists of 1h ON and 3h OFF.

Judgment Criteria :

Judgment Criteria are due to the limits of the electrical characteristics in the detail specification.

Estimated date for qualification completion: 31 July 2016

List of affected Standard Parts:

Part Number	Qualification Vehicle
LV8282PV-TLM-H	LV8281VR
LV8702V-TLM-H	LV5236VZ